

DAF TAPE ADHERING APPARATUS AND DAF TAPE ADHERING METHOD

5

ABSTRACT OF THE DISCLOSURE

A method for adhering a DAF tape, and a DAF tape
adhering apparatus using the method, are provided. A
wafer is secured on a stage in a lower kiln, a DAF tape
is held by the lower kiln and an upper kiln arranged to
be opposed to the lower kiln, and further, the pressure
in the upper kiln is made relatively higher than the
pressure in the lower kiln so as to swell the DAF tape
and to adhere the DAF tape to the wafer. A table movable
toward the DAF tape can be adopted. Further, an air
supply part may be provided in the upper kiln. The
pressure in the upper kiln may be made higher than the
pressure in the lower kiln by supplying air from the air
supplying part. A vacuum source connected to the lower
kiln may be provided so as to reduce the pressure in the
lower kiln. Formation of wrinkles on the DAF tape and
trapping of air bubbles under the DAF tape can be
prevented.